

SAMSUNG SM-G965F Schematic Diagram



Schematic *Diagram*



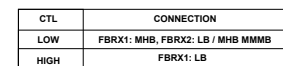
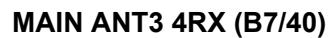
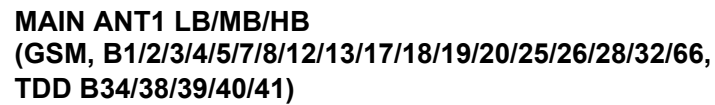
SM-G965F_REV0.9

Mobile1Tech.com


- sheet01 : RF1 - MAIN_ANT
- sheet02 : RF2 - SUB ANT
- sheet03 : AP(EXYNOS9810) CP , UFS MEMORY
- sheet04 : CONNECTIVITY , SENSOR
- sheet05 : LHOTSE & ETC
- sheet06 : LHOTSE ,Mobile1Tech.com
- sheet07 : AP PMIC, IF PMIC
- sheet08 : AUDIO CODEC, SUB PCB
- sheet09 : VISUAL PART 1/2
- sheet10 : CON10001
- sheet11 : RF3 - MHB MMMB FOR SCC & AS (EU NC)
- sheet12 : UPDATED

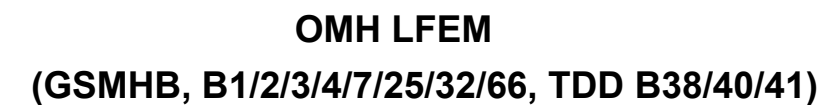
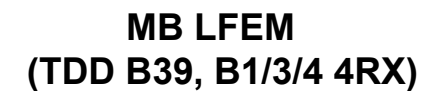
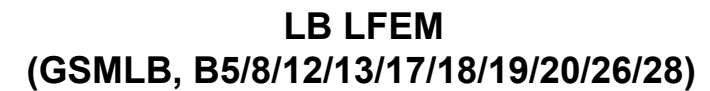
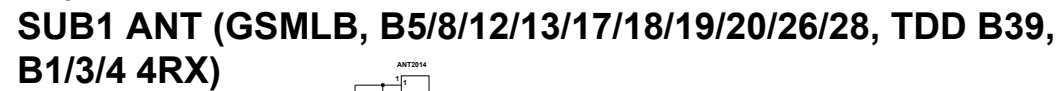
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Drawn By:	
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DOC CTRL CHK:	
RF3 ENGR CHK:	
SA CHK:	REV: <div>1</div>

Changed By:	Date Changed:	Time Changed:	SA CHK:	REV:	Drawing Number:	Page:
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**S735 ET MODULATOR
(KOR : MB/HB PAMID)**

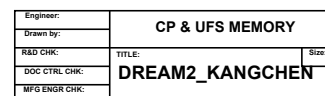
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Drawn by: user20		
R&D CHK:		TITLE:
DOC CTRL CHK:		
MFG ENGR CHK:		Size: 16 1 12 A



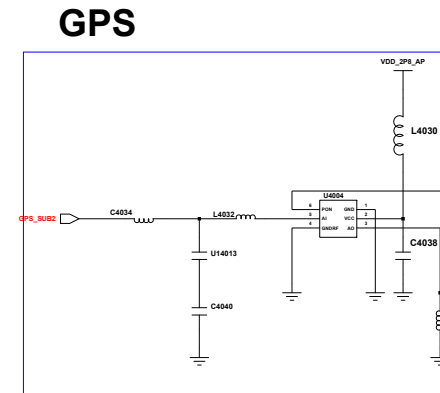
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T-FLASH / SIM / PROXY / IRIS LED / RGB

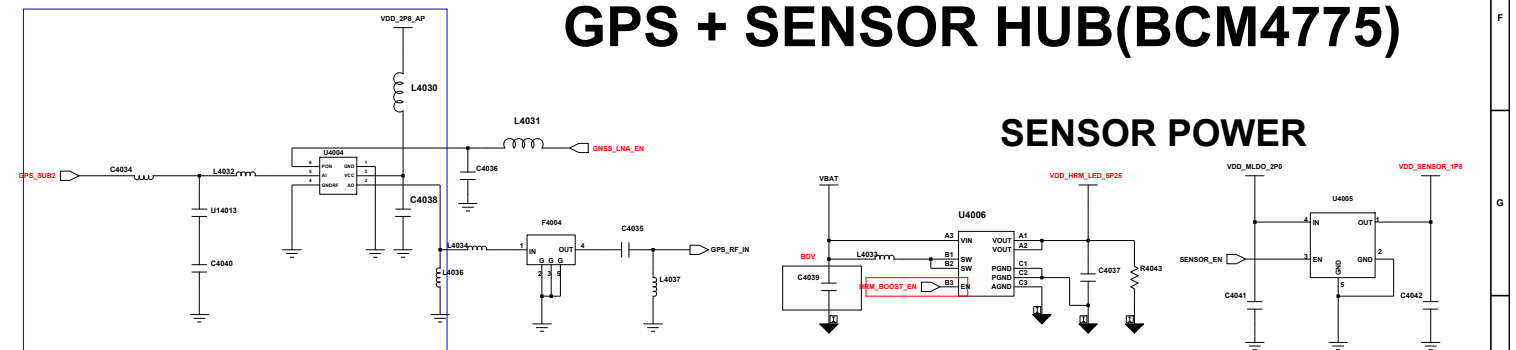


SENSORS

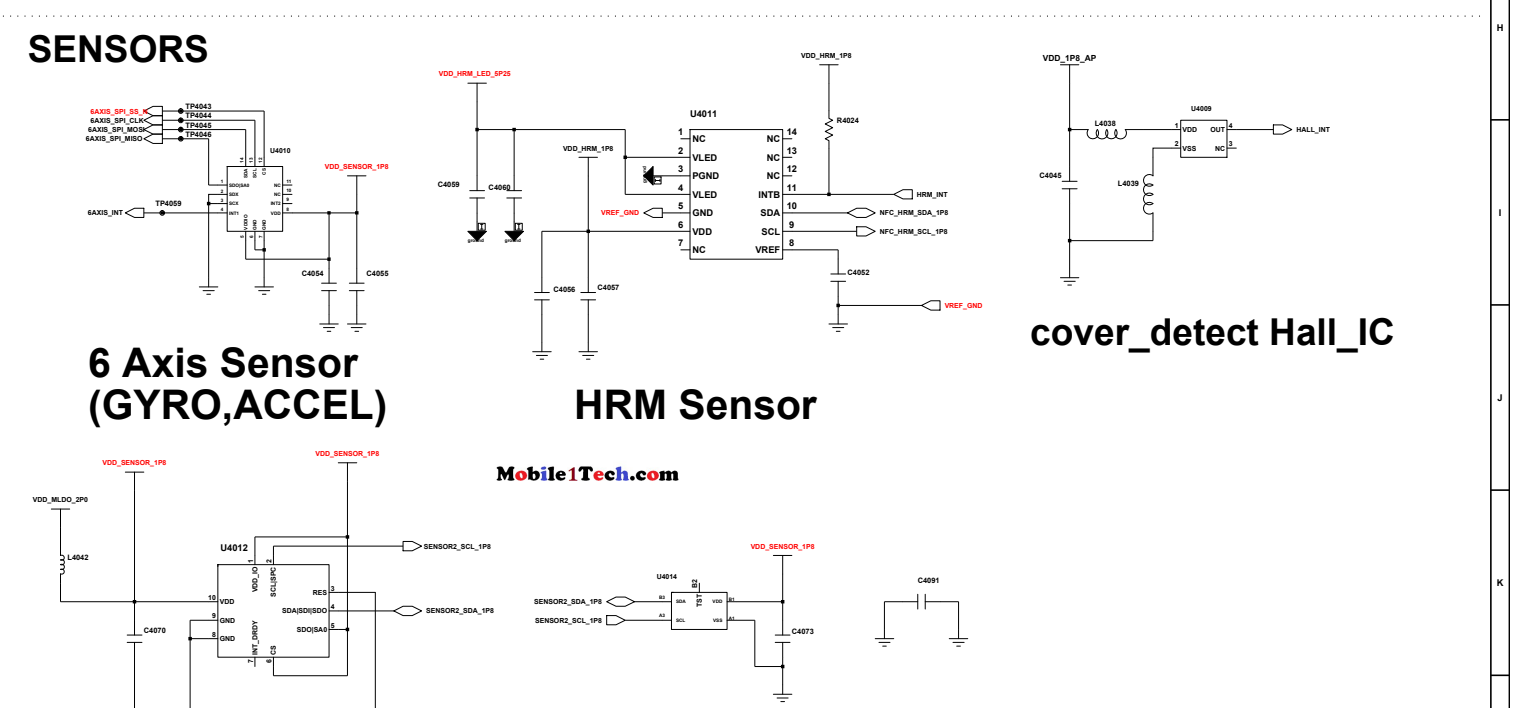


GPS + SENSOR HUB(BCM4775)

SENSOR POWER



NFC



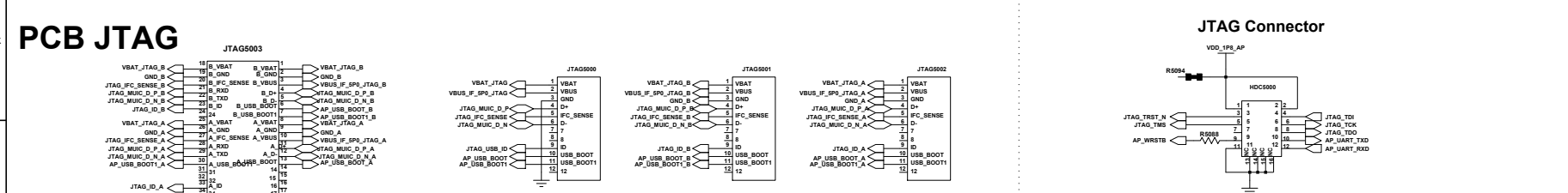
6 Axis Sensor (GYRO,ACCEL)

HRM Sensor

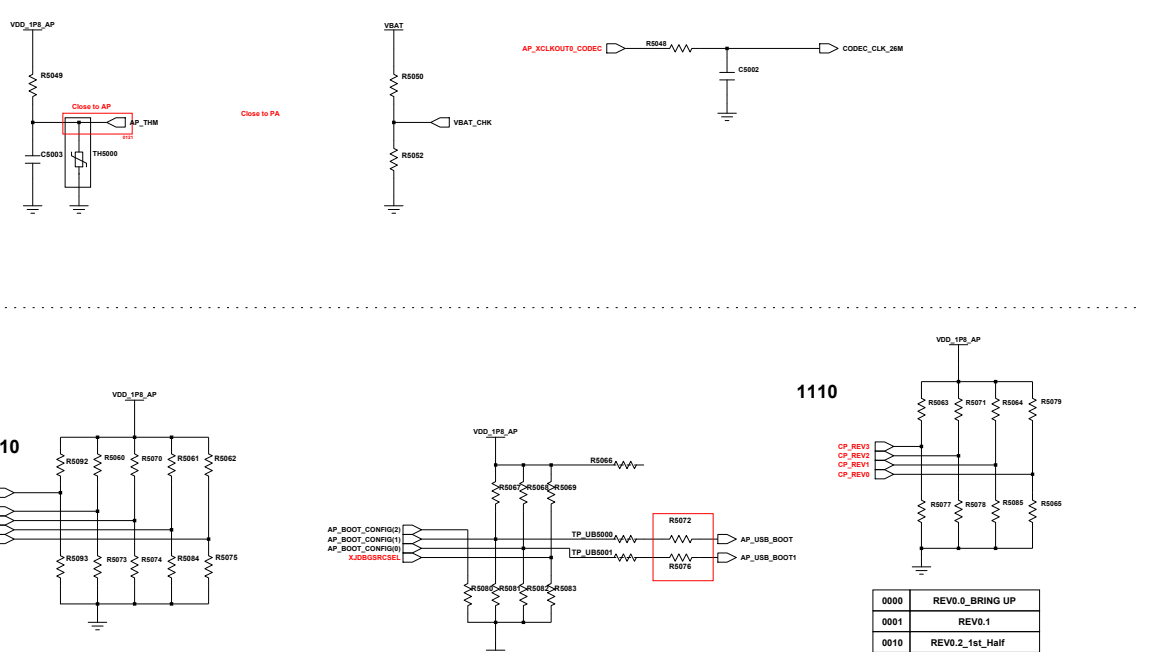
Barometer Sensor

MAGNETIC SENSOR

UCP500-1



TC



0000	REV0.0_BRING UP
0001	REV0.1
0010	REV0.2_1st_Half
0011	G965F REV0.0
0100	G965F REV0.1
0101	G965F REV0.1+EV1+MD05
0110	G965F REV0.2
0111	G965F REV0.3
1000	G965F REV0.4
1001	G965F REV0.5
1010	G965F REV0.6
1011	G965F REV0.7
1100	G965F REV0.8
1101	Network Lock Algorithm
1110	G965F REV0.9

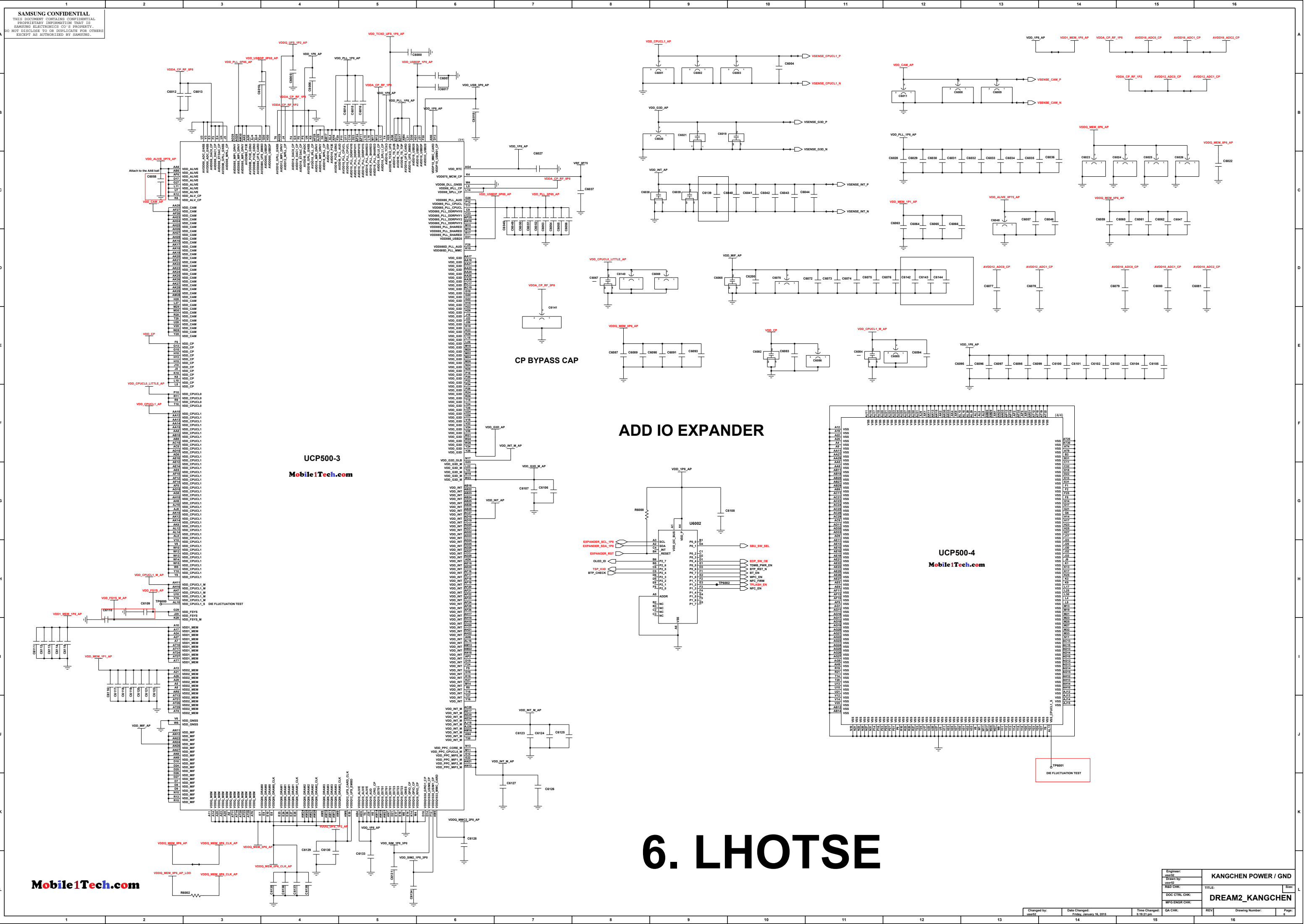
KANGCHEN & ETC

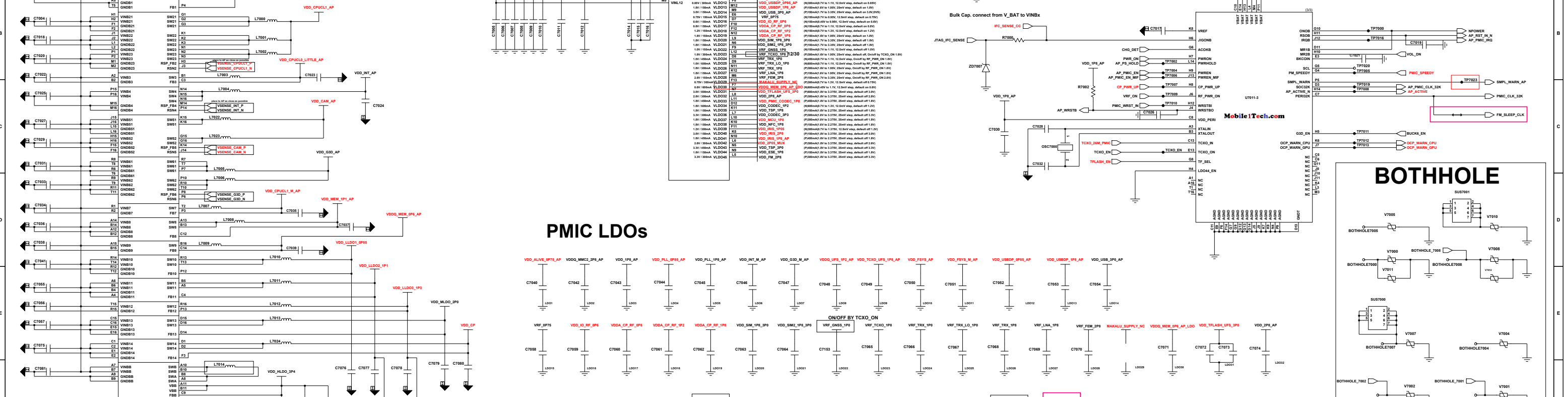
BEAM2_KANGCHEN

REAMZ_KANGCHEN

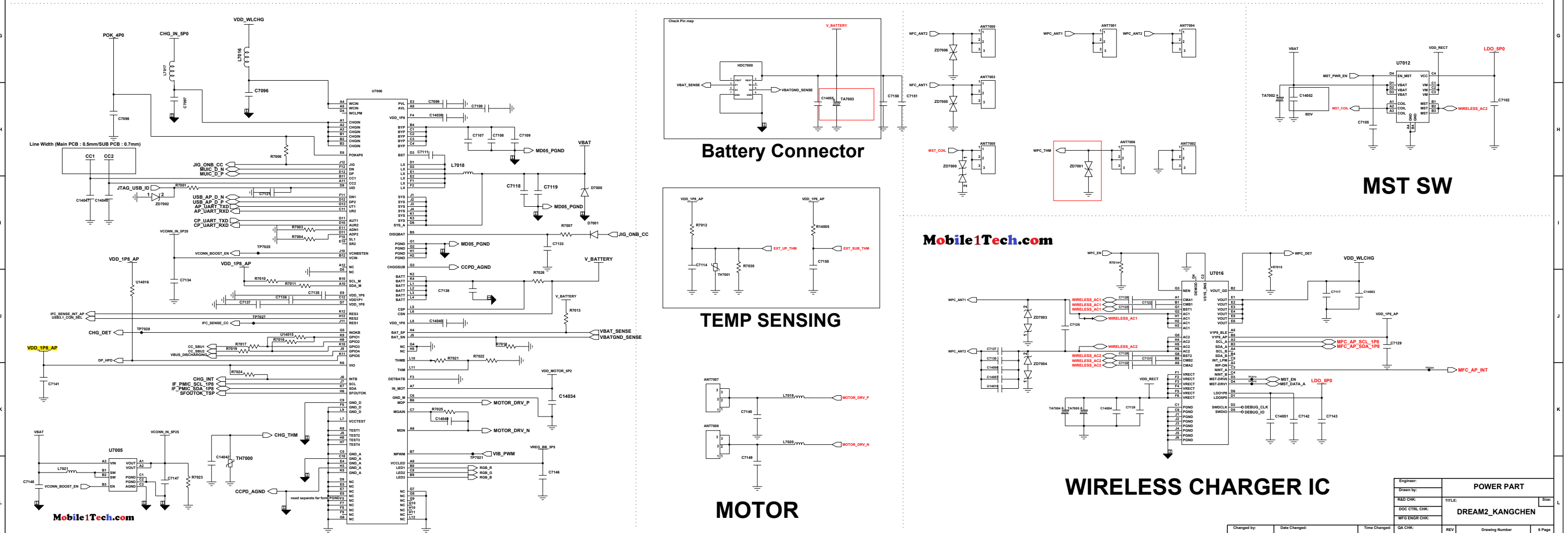
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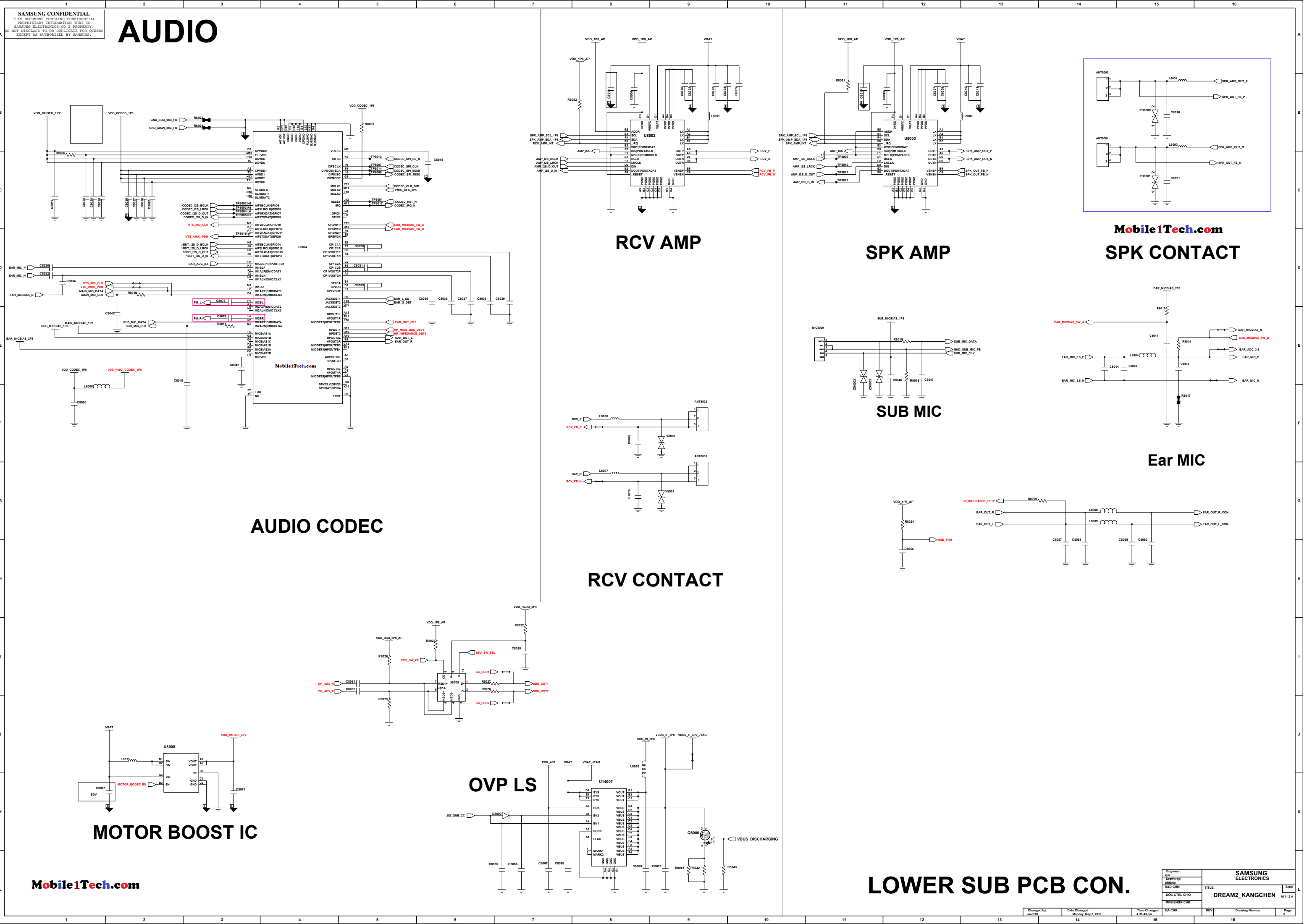
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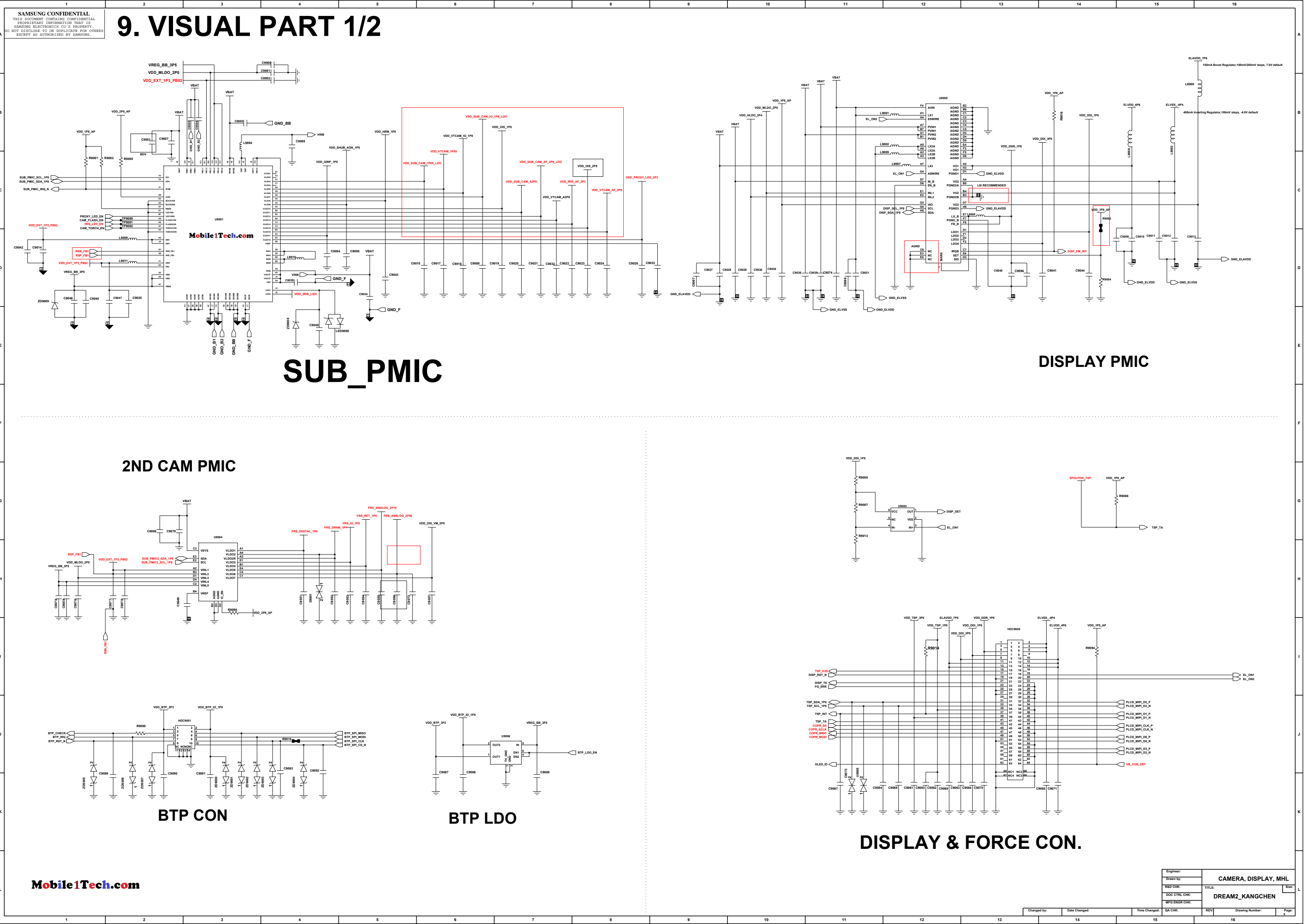


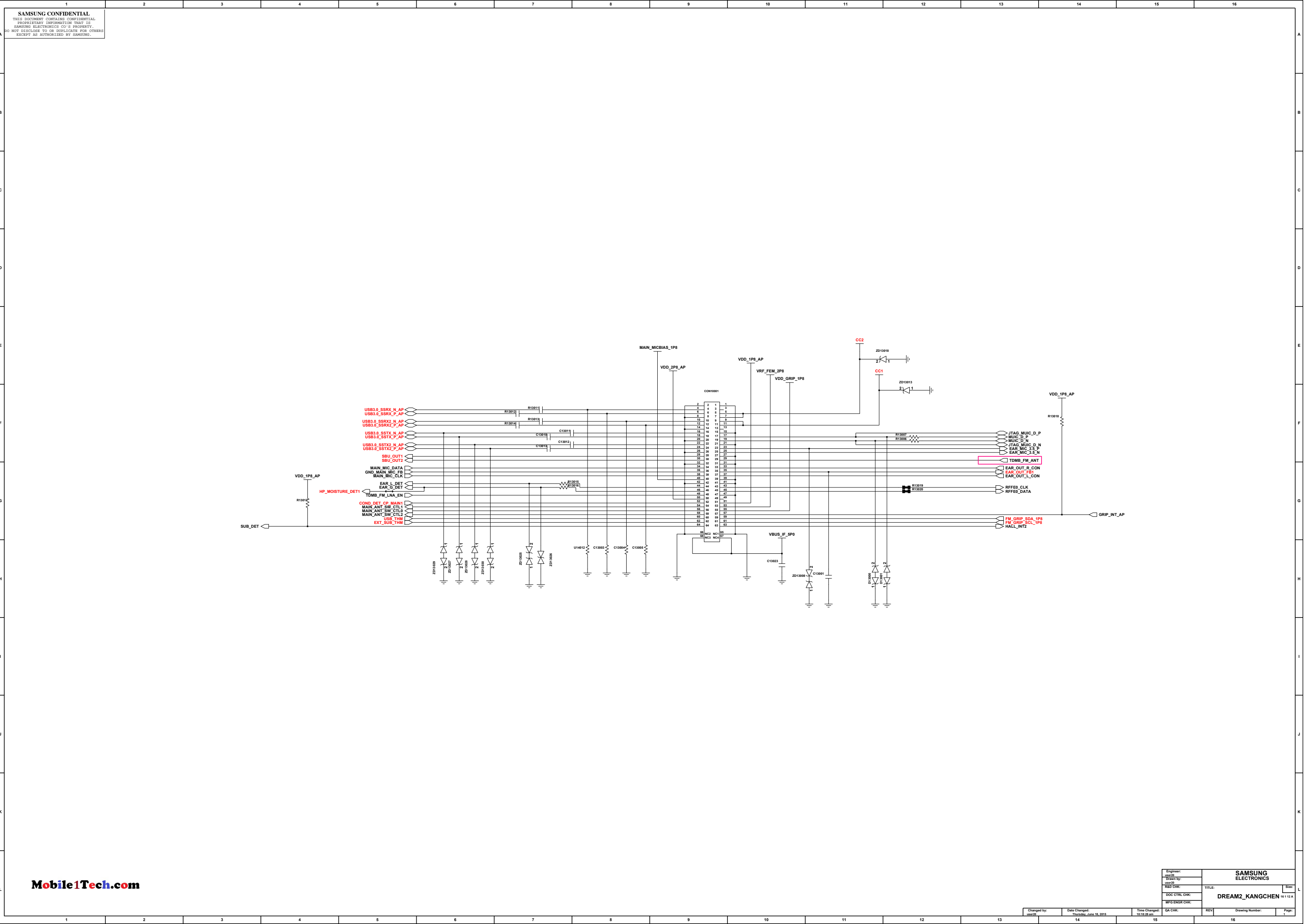
[illegible]

The schematic diagram illustrates the AP PMIC (Application Processor Power Management Integrated Circuit) circuit. It features a series of capacitors (C7082, C7083, C7084, C7166, C7167, C7086, C7087, C7089, C7090, C7091, C7092, C7093, C7094, C7088, C14050, C7160) and inductors (L2003, L2004, L2005, L2006, L2007, L2008, L2009, L2040, L2041, L2042, L2043, L2044, L2045) connected to various power rails. Key components include the VDD_PMIC_CODEC_1P9, VDD_CODEC_1P2, VDD_TSP_1P9, VDD_CODEC_3P3, VDD_MCU_1P9, VDD_NFC_1P9, VDD_RIS_1P06, VDD_RIS_2P9, VDD_RIS_1P9_AP, VDD_3P95_MUX, VDD_TSP_3P9, VDD_ESE_1P9, VDD_M_3P9, V7009, and V7003. The diagram also shows connections to the BOTHERHOLE7002, BOTHERHOLE7001, BOTHERHOLE7009, and BOTHERHOLE7003.





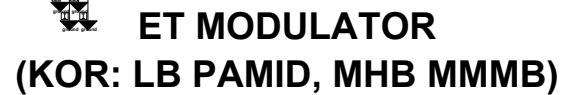




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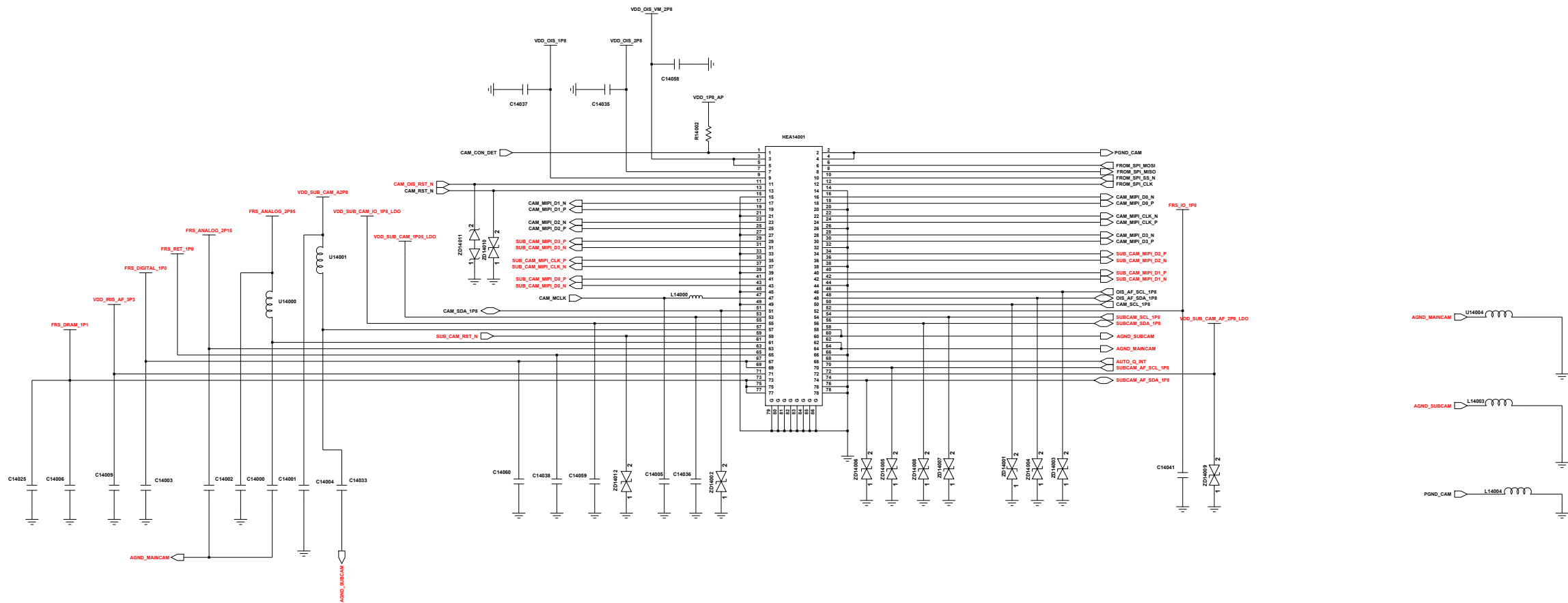


MHB MMMB (B1/3/7 SCC & AS)

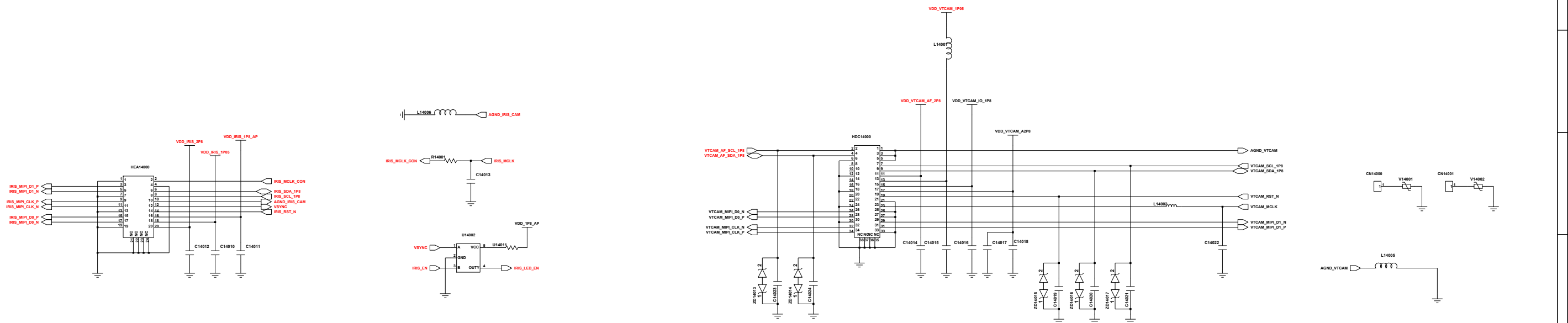


Shieldcan





UPDATED



UPDATED